

Micromegas DHCAL

Status Report and Future Plans

CALICE Meeting

UT Arlington, Texas

12th March 2010

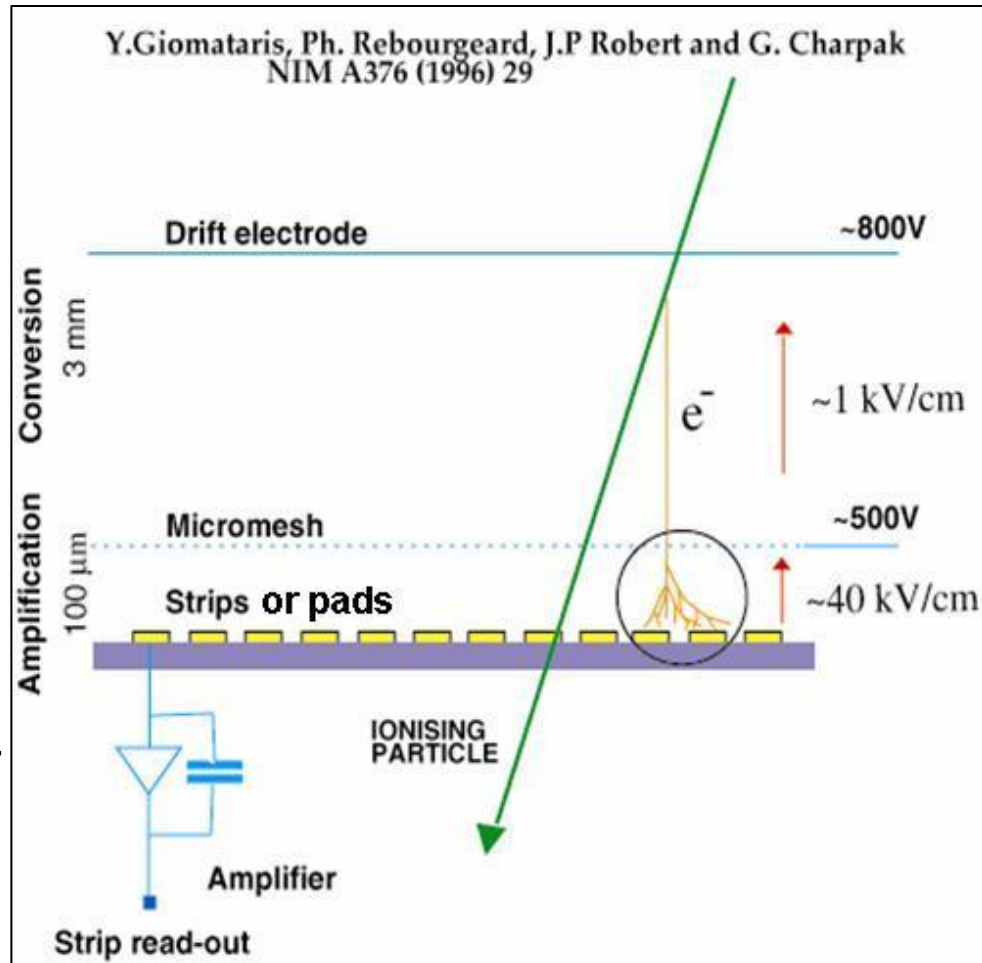
Ambroise Espargilière on behalf of the LAPP group

Outline

- Brief reminder
 - Prototype characteristics
 - Electronic realisations
 - Bulk Micromegas with embedded readout electronics
- Beam tests results
 - Analog readout
 - HARDROC 1-2
 - DIRAC2
- 2010 plans
 - VFE Electronics developments (readout ASIC, spark protection)
 - First m² technological prototype status
 - Beam tests
 - Simulation activities
- Conclusion

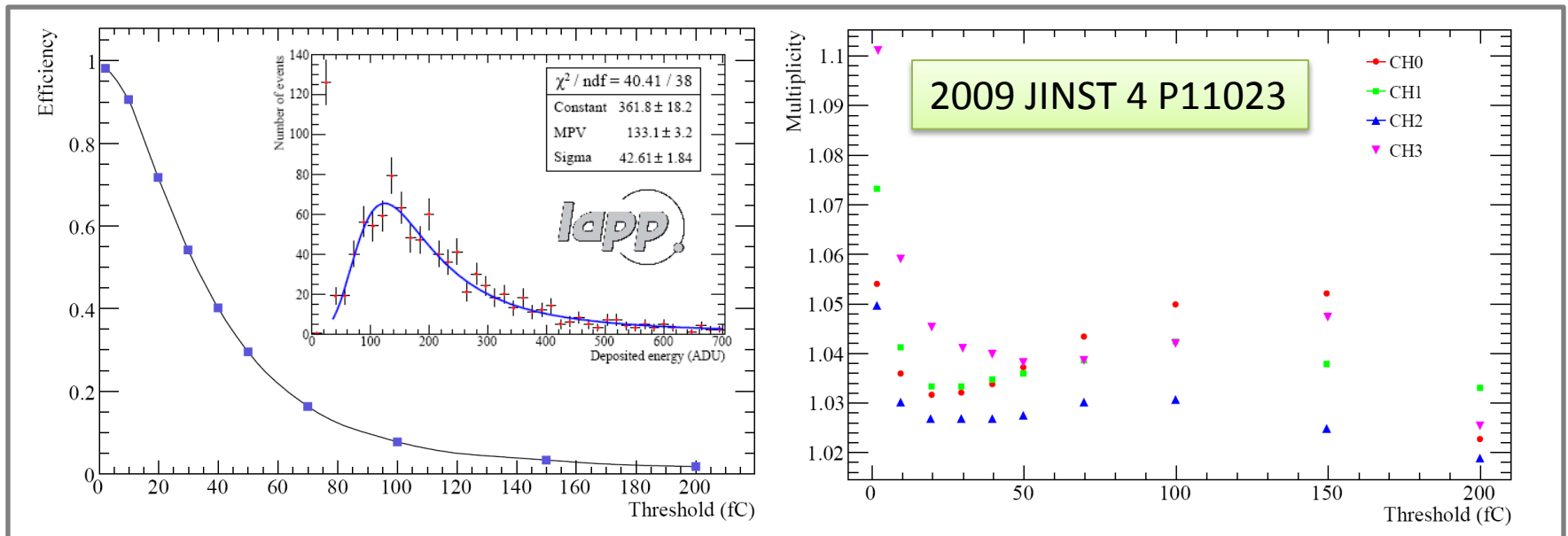
Reminder: MICROME GAS

- MICROME GAS detector
 - MICRO MESH Gaseous Structure
 - High detection rate
 - Low voltage (all < 600V)
 - Bulk technology
 - Robust, cheap
- Prototype layout
 - 128 μm bulk
 - 3 mm conversion gap
 - 2 mm absorber as chamber cover



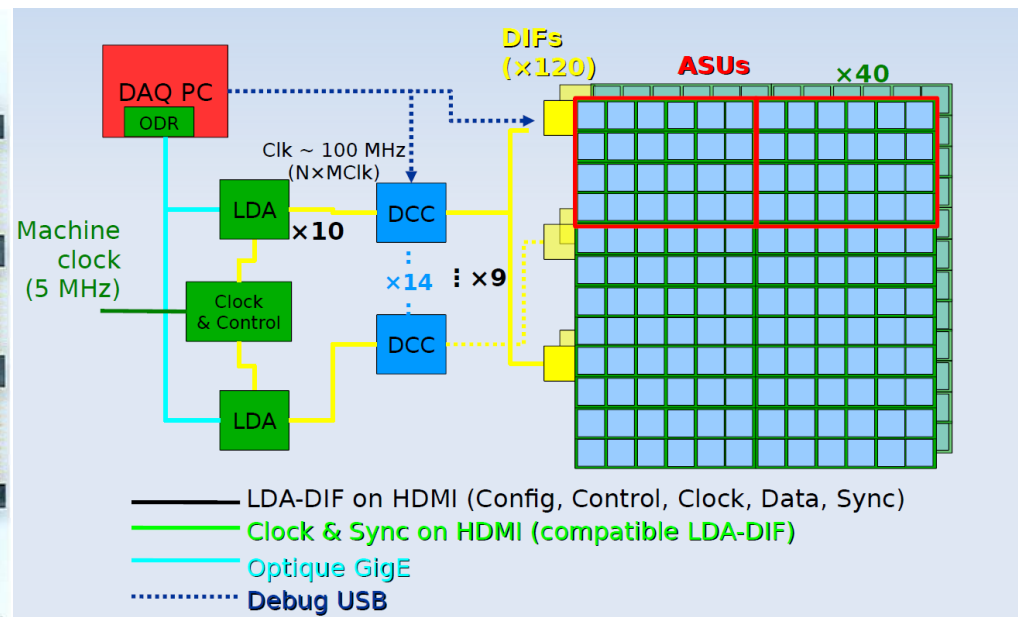
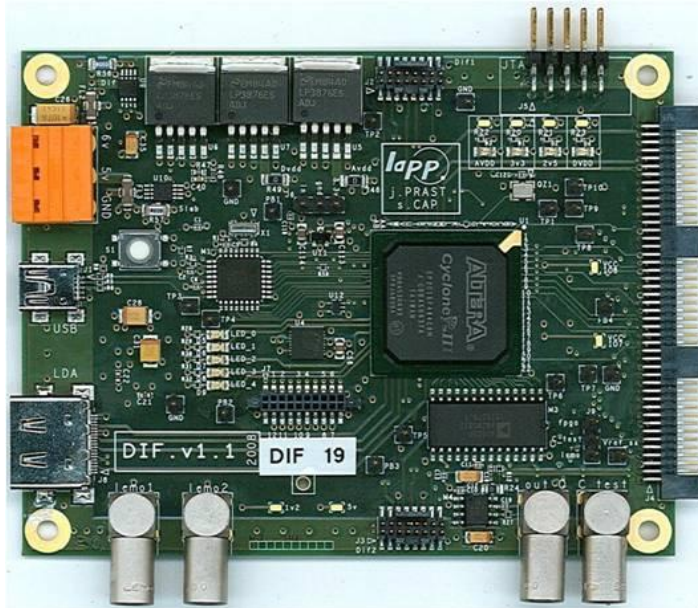
Reminder: basic performance

- Prototype basic performances (test beam 2008)
 - MIP most probable value : $\sim 20\text{fC}$ (11% r.m.s.)
 - Efficiency $> 97\%$, channel non-uniformity $< 1\%$ (1.5fC threshold)
 - Multiplicity < 1.1 , chamber non-uniformity $< 1.5\%$



Reminder: Electronics (see C. de la Taille's talk)

- DIF (Detector Interface) developed at LAPP and ready for mass production
- Recent developments for the new CALICE DAQ:
 - 8B/10B Communication protocols validated (LAPP/LLR)
 - CCC (Clock and Control Card) integration in work at LAPP

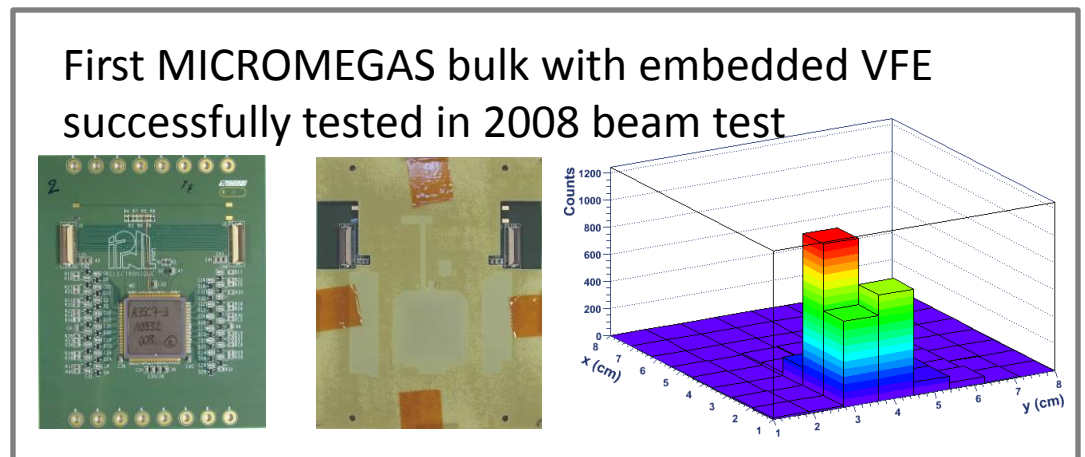


Digital Readout

- Bulk MICROMEGAS with embedded Readout electronics
 - HCAL compactness \Rightarrow embedded VFE
 - Install bulk or VFE first ? ASICs won't survive being laminated
Bulk won't behave well in the soldering oven
 - \rightarrow Solution: VFE first with protection mask for the ASICs

2 types of ASICs considered

- HARDROC , 2 versions (LAL)
- DIRAC2 (LAPP/IPNL)

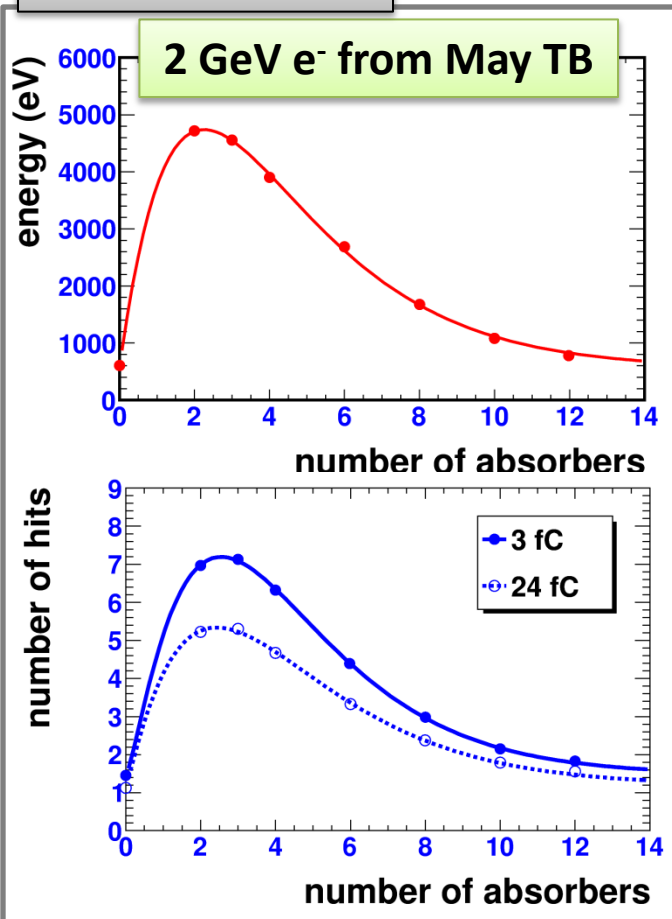


2009 Beam tests results summary

SEPT 2009: GASSIPLEX

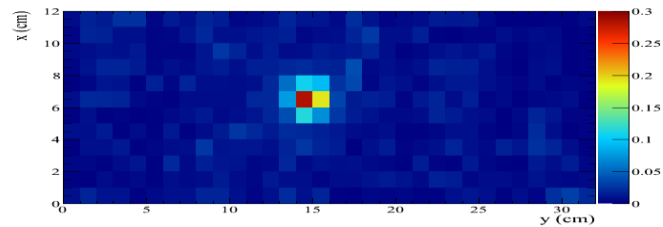
- hadron showers (1-6 GeV, 6 Abs.)

Previous Results

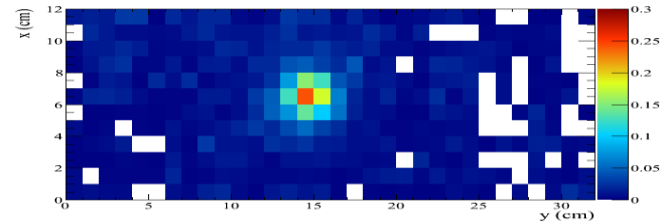


Ongoing analysis

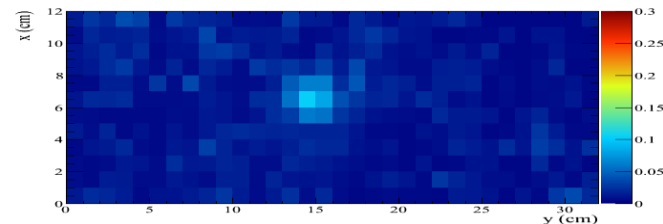
Hadrons 1 GeV



0 absorber



3 absorber



6 absorber

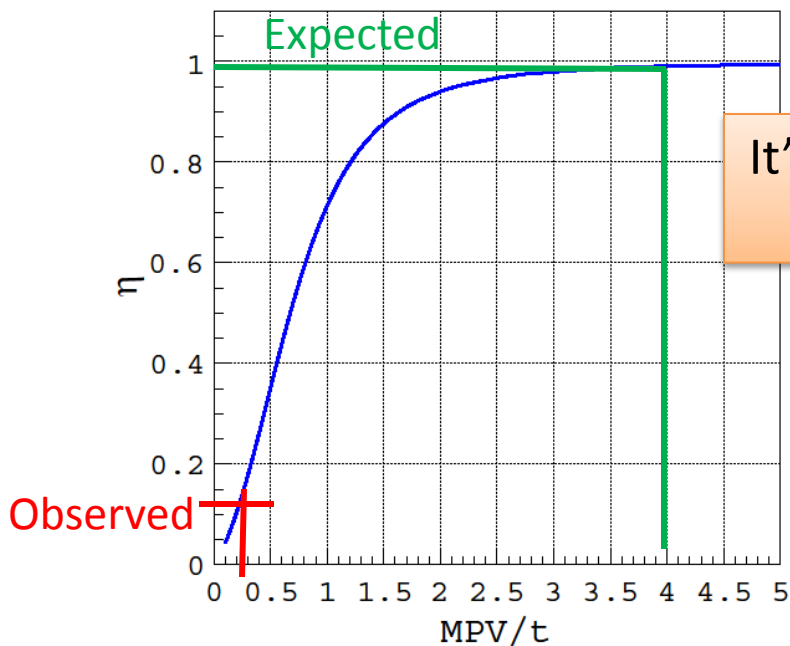
Ambroise Espargiliere (LAPP)
CALICE meeting at UT Arlington

12x32 cm² chamber

2009 Beam tests results summary

SEPT 2009 : HARDROC 1

- Threshold $\sim 5fC \rightarrow$ expect $\sim 90\%$ efficiency or more
- Measurement $\rightarrow 8 - 14\%$ (extremely low !!)



It's like if the MPV were only $\sim 1fC$ ($MPV/t = 0.25$) instead of $\sim 20fC$

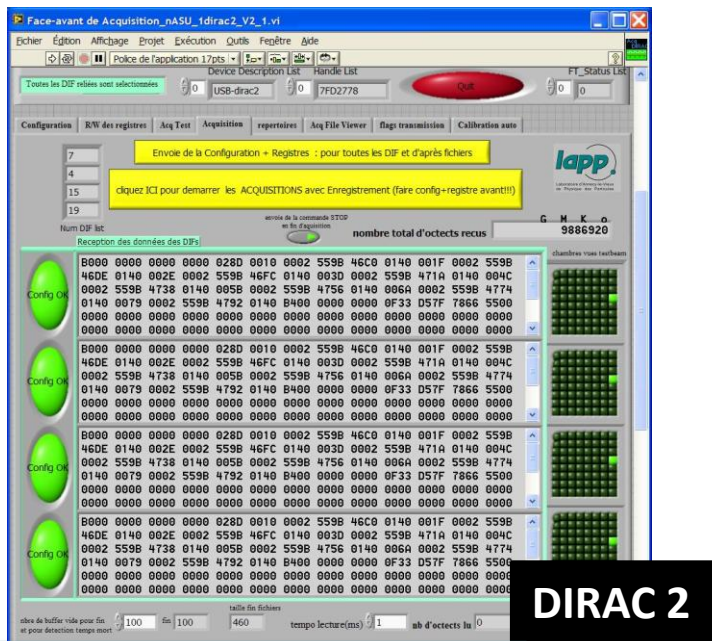
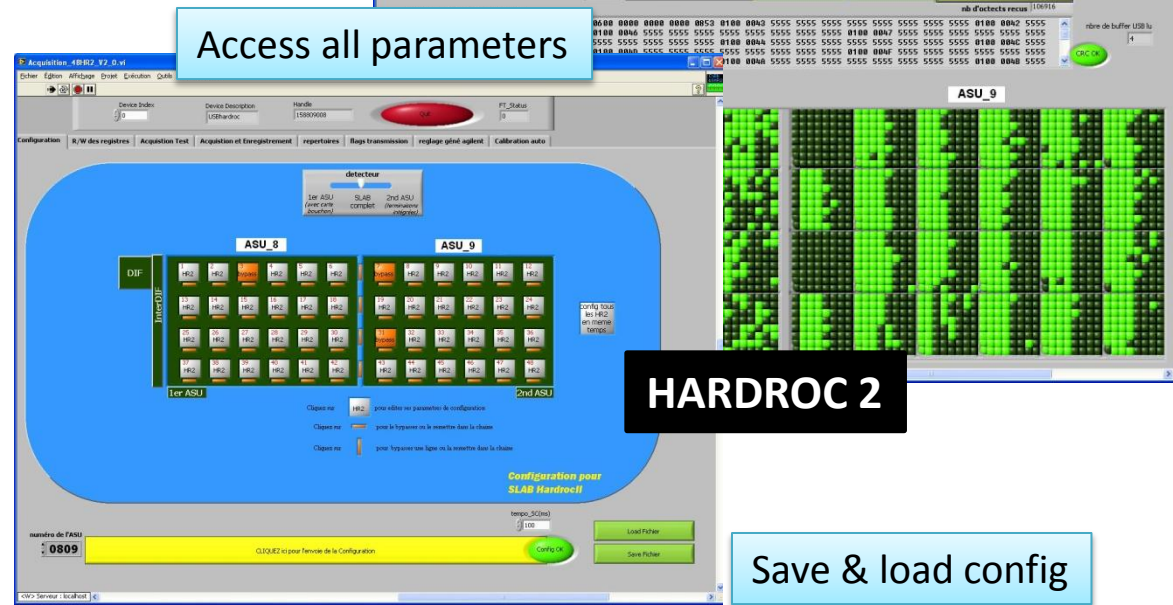
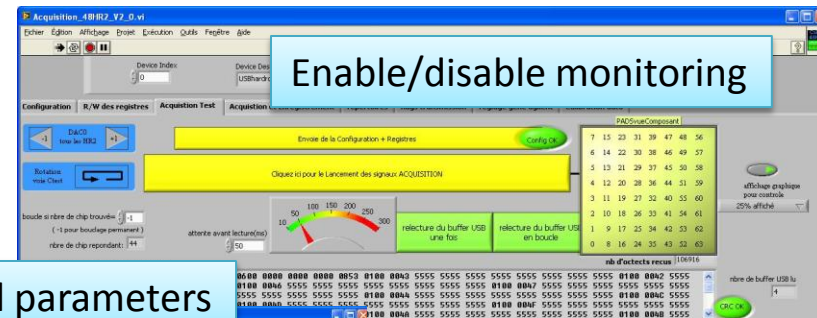
2009 Beam tests results summary

SEPT 2009 : HARDROC 1

- MICROMEAS signal
 - Fast electron signal (~ 1 ns)
 - Slow ion signal (~ 100 ns)
 - $\sim 90\%$ signal due to ions ($e^-/\text{ions} = 1/\ln(\text{Gain}) \approx 0.1$)
- HARDROC shaping time very short (10-20 ns)
 - electron drift velocity ($\sim 50 \mu\text{m}/\text{ns}$)
 - only one mm of gas is seen (2/3 signal lost)
 - the ion tails can't be seen ($\sim 90\%$ of signal lost)
 - HARDROC sees only $0.1 \times 1/3 \times 20\text{fC} \approx 1\text{fC}$ as signal MPV

New acquisition software

- X-DAQ left out
- Labview software for calibration, monitoring and data acquisition
- Version for HR1, HR2, DIRAC2
- Version for hybrid readout foreseen
- ~ 100Hz acquisition rate (24 HR2)



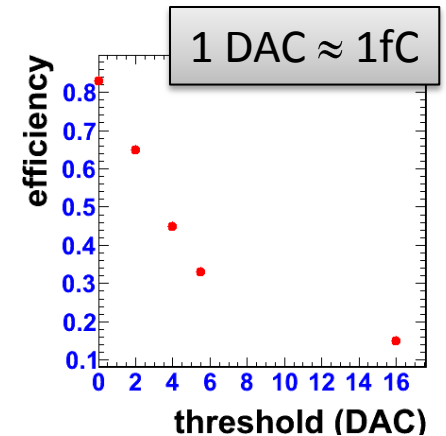
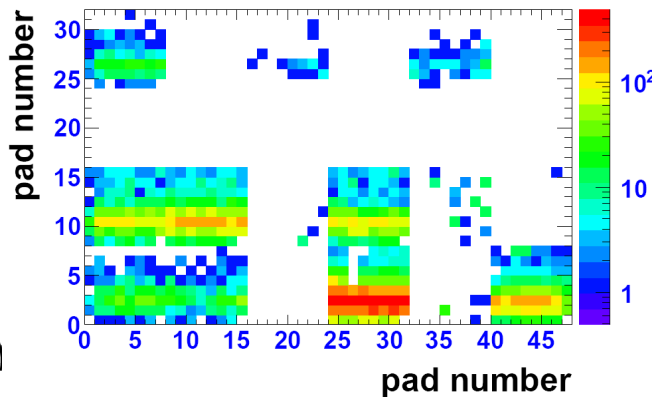
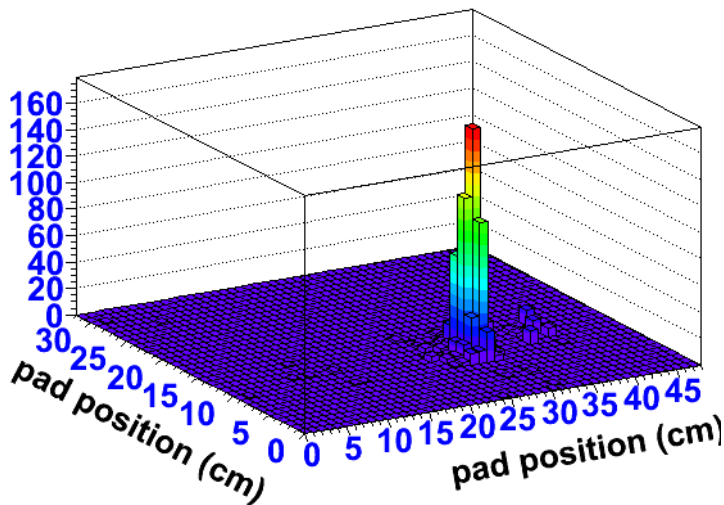
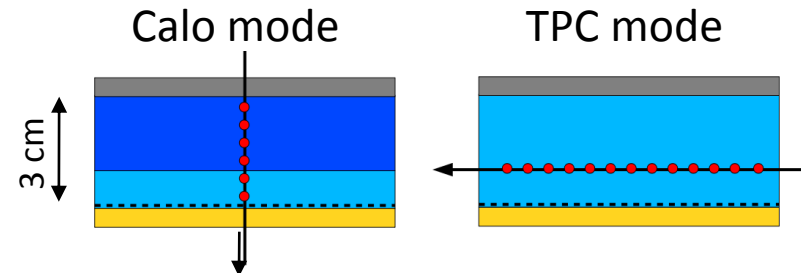
Monitor 4 chambers at once

Ambroise Espargiliere (LAPP)
CALICE meeting at UT Arlington

2009 Beam tests results summary

NOV 2009: HARDROC 2

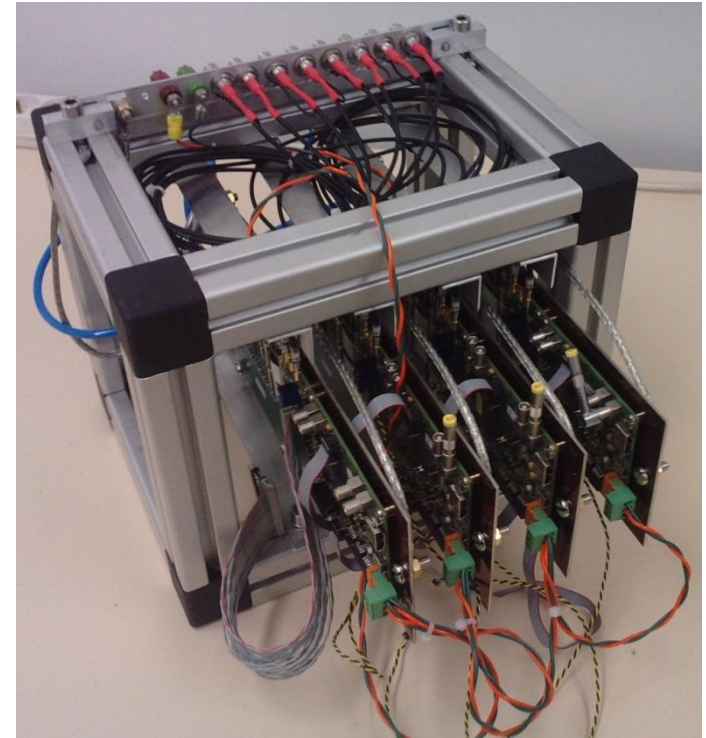
- One 32x48 ASU in test box
- Beam profile
- Efficiency very low (as expected with HARDROC)
 - measurements via « self tracker » or « TPC » mode (1cm gas)
- Many chips were dead (reason not obvious)



2009 Beam tests results summary

NOV 2009: DIRAC 2

- Stack of 4 8x8 MICROMEAS chambers equipped with DIRAC 2
- Only 3 hours commissioning
- 4-fold coincidences immediately observed
- Destructive sparks killed channels one by one after few hours functioning
 - Few data available
 - No time for threshold optimisation



2009 Beam tests results summary

NOV 2009: DIRAC 2

Very Preliminary

- DIRAC performances

(no threshold optimisation)

Compatible with previous measurements

Multiplicity

Chamber 1: 1.13 (6fC)

Chamber 2: 1.11 (6fC)

Chamber 3: 1.07 (14fC)

Chamber 4: 1.06 (14fC)

Efficiency

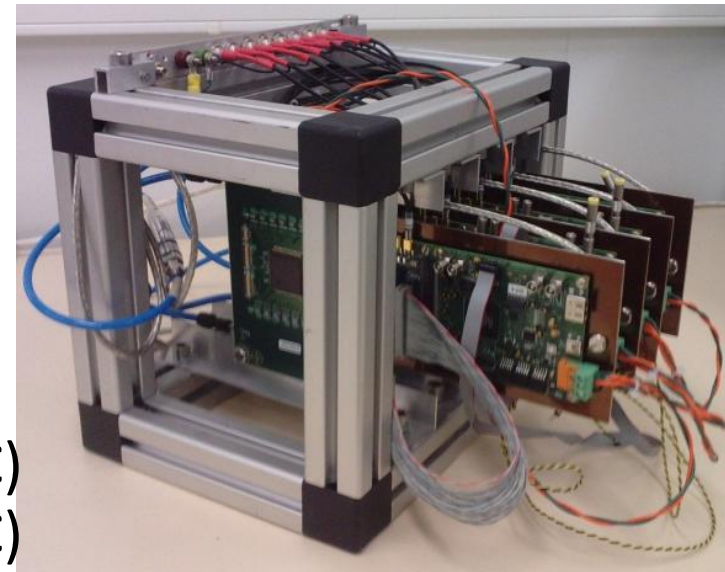
Chamber 1: $12 / 27 = 0.4 \pm 0.1$ (6fC)

Chamber 2: $14 / 29 = 0.5 \pm 0.1$ (6fC)

Chamber 3: $14 / 30 = 0.5 \pm 0.1$ (14fC)

Chamber 4: $14 / 30 = 0.5 \pm 0.1$ (14fC)

Not corrected for synchronous functioning



Digital readout

Conclusions and outlook

- HARDROC 1 and 2 input stage not adapted to MICROMEAS signal
- DIRAC 2 showed fragility to sparks
- HARDROC showed fragility not fully explained (sparks ? Commissioning ? ...)
- New chip is needed
 - Optimized for MICROMEAS signal
 - Hardened design against sparks
- Improved external spark protection needed

2010 plans :

VFE Electronics developments

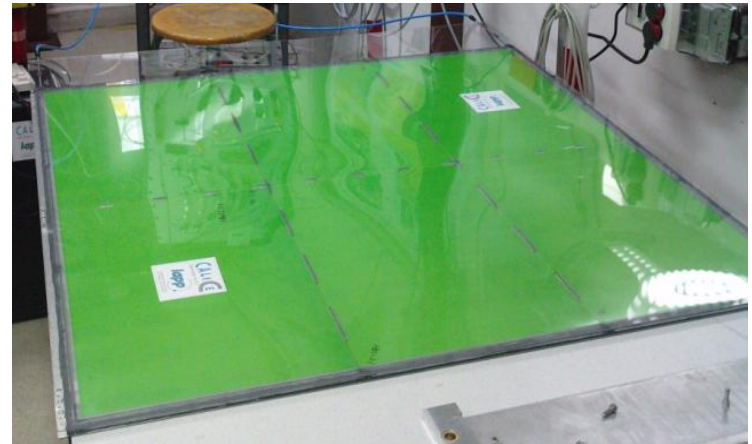
- New input stage developed for the next generation ASIC
 - Optimized for MICROMEGAS
 - Simulations give $S/N=10$ @ 1fC, noise r.m.s. 0.1fC @80pF
 - Integrable to HARDROC or DIRAC design
- Spark protections
 - PCB to test various protection schemes
 - Spark generator (large capacitance discharging in the PCB)
 - Test of buried components undergoing and promising

Preliminary

2010 plans:

First technological m² prototype (1)

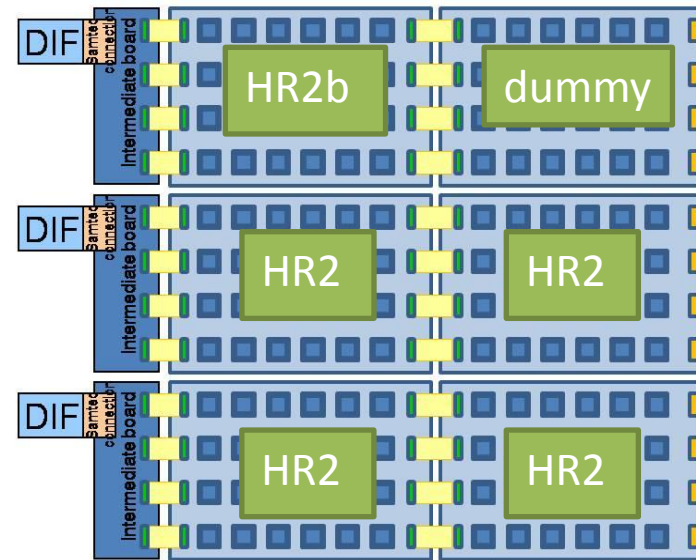
- Mechanical Prototype validated the assembly procedure (6 dummy ASUs)
- Available ASU for technological prototype
 - 4 ASU with HARDROC2 chips
(under tests, almost all ready)
 - 1 ASU with HARDROC2b chips
(PCB in cabling)
 - 1 dummy ASU (6 ASU 32x48 are necessary)



2010 plans:

First technological m² prototype (1)

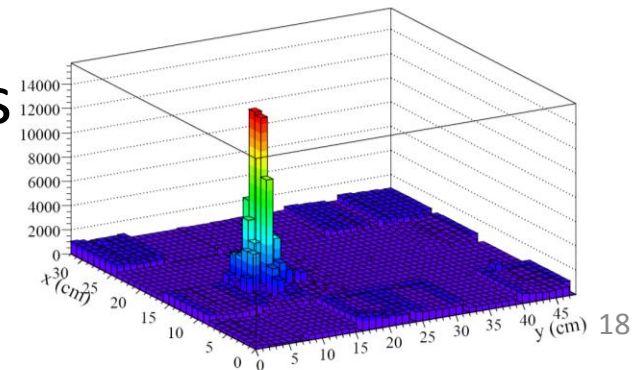
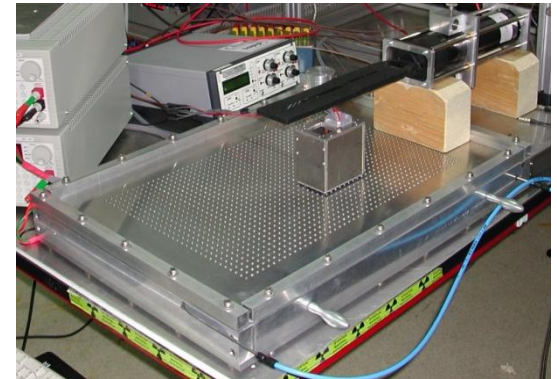
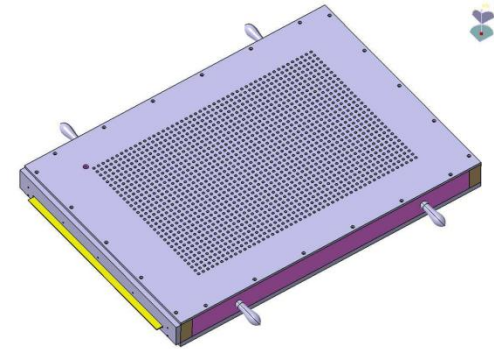
- Mechanical Prototype validated the assembly procedure (6 dummy ASUs)
- Available ASU for technological prototype
 - 4 ASU with HARDROC2 chips (under tests, almost all ready)
 - 1 ASU with HARDROC2b chips (PCB in cabling)
 - 1 dummy ASU (6 ASU 32x48 are necessary)



2010 plans:

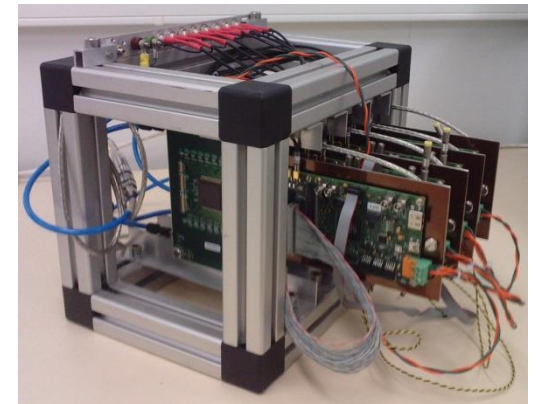
First technological m² prototype (2)

- All ASU tested between each step
 - Electronics:
 - Return from cabling
 - Return from bulk lamination
 - After bulk cooking
 - Full calibration
 - ⁵⁵Fe and/or cosmics with a test box
- Clean room → naked mesh ASU
 - Perform mesh cooking in air
 - Insert/remove ASU from test box
- m² completion
→ validate full design & processes



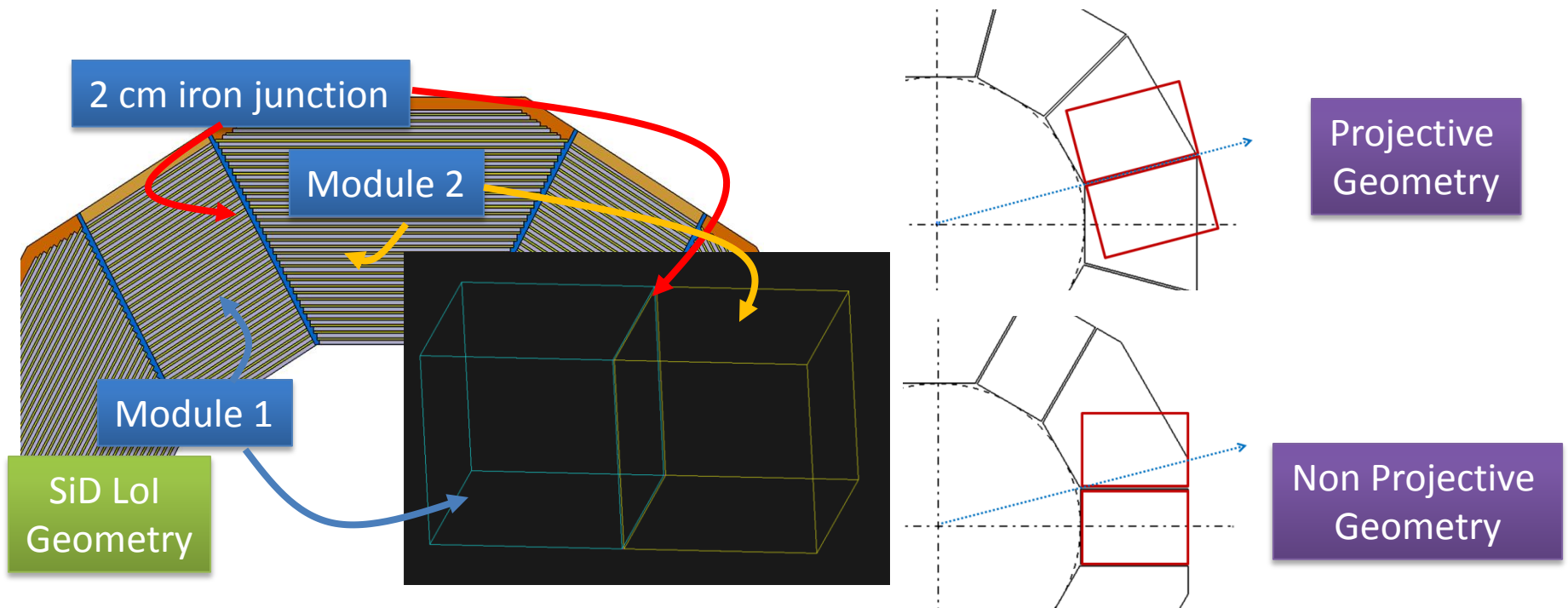
2010 plans: Beam tests

- Beam test second half of June 2010 at CERN/SPS/H4
 - m^2 tests
 - Test m^2 functionality
 - Measure efficiency, multiplicity and uniformity
 - Use HR1 or DIRAC ministack stack as a telescope
 - DIRAC tests
 - Measure efficiency, multiplicity and uniformity
 - Test power pulsing in magnetic field
 - Spark study
- Beam test mid November 2010 at CERN/PS
 - m^2 tests in/behind W structure

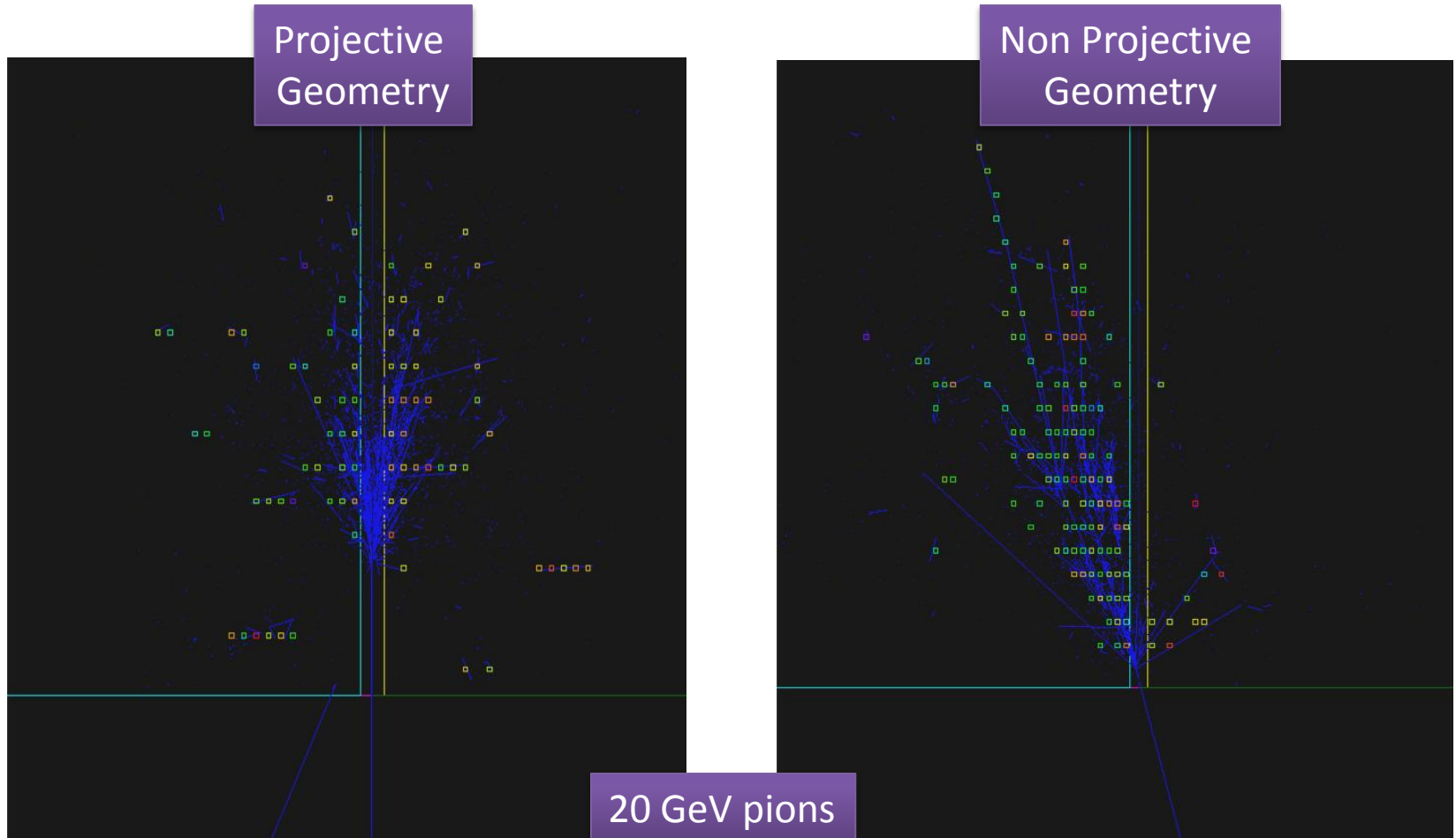


2010 plans: Simulation activities

- Study impact of supporting structure on the HCAL performance
- Projective and non-projective geometries are considered



2010 plans: Simulation activities



Conclusion

- Project delayed
 - HARDROC 1 & 2 not applicable to MICROMEAS
 - DIRAC 2 not spark proof
- Main benchmarks:
 - Commissioning of m² technological prototype
 - Optimized readout chip
 - Upgraded spark protections
- Intensive R&D activities
 - LAPP group is involved in several fields (DIF task force, Mechanical engineering, detector R&D, simulations)
 - Detector R&D highly supported by in2p3